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Amend B
Y Robinson
5/17/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: OPTOELECTRONIC SEMICONDUCTOR PACKAGE DEVICE
Serial No.: 10/082,500 Filed: February 25, 2002
Examiner: Chu, C. Group Art Unit: 2815
Atty. Docket No.: BDG005-3

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

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01 FC:1000 110.00 CH
02 FC:2000 756.00 CH

RESPONSE

In response to the Office Action dated April 10, 2003, please amend the application as follows.

In the Specification

Replace the paragraph at page 3, lines 13-20 with the following paragraph:

Optoelectronic packages for optical sensors often include a chip carrier, an optoelectronic chip mounted in a cavity of the chip carrier, and a transparent window positioned above the chip that hermetically seals the cavity and passes through the incident light to the chip. The optoelectronic chip typically includes a light sensitive cell that comprises an array of tiny photosensor elements, such as charge coupled devices (CCDs) or complimentary metal oxide semiconductor (CMOS) photoreceptors. The photosensor elements convert the light energy incident upon them into electrical signals on an element-by-element or pixel-by-pixel basis. These signals convey information about the intensity, color, hue, saturation and other attributes of the incident light.